

Solid State Relay OCMOS FET

<u>PS7241-2A</u>

8-PIN SOP, 400V BREAK DOWN VOLTAGE NORMALLY OPEN TYPE 2-ch Optical Coupled MOS FET

-NEPOC Series-

DESCRIPTION

The PS7241-2A is a solid state relay containing GaAs LEDs on the light emitting side (input side) and normally open (N.O.) contact MOS FETs on the output side.

It is suitable for analog signal control because of their low offset and high linearity.

FEATURES

- 2 channel type (1 a + 1 a output)
- Low LED operating current (IF = 2 mA)
- Designed for AC/DC switching line changer
- Small and thin package (8-pin SOP, Height = 2.1 mm)
- Low offset voltage
- Ordering number of taping product : PS7241-2A-F3, F4: 1 500 pcs/reel
- <R> Pb-Free product
 - · Safety standards
 - UL approved: File No. E72422
 - BSI approved: No. 8241/8242
 - CSA approved: No. CA 101391

APPLICATIONS

- · Exchange equipment
- · Measurement equipment
- FA/OA equipment

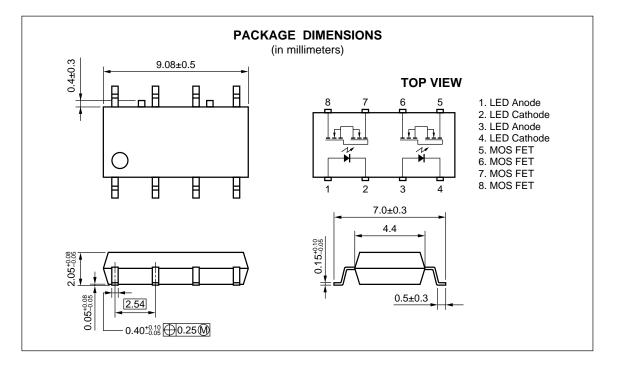
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Document No. PN10304EJ02V0DS (2nd edition) Date Published August 2006 NS CP(K)

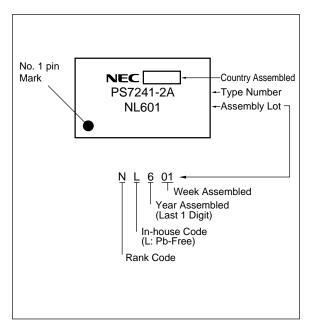
The mark <R> shows major revised points.

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The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.



<R> MARKING EXAMPLE



<R> ORDERING INFORMATION

| Part Number | Order Number | Solder Plating Specification | Packing Style | Safety Standard Approval | Application Part Number*1 |
|--------------|----------------|---------------------------------|------------------------------|-----------------------------|------------------------------|
| PS7241-2A | PS7241-2A-A | Pb-Free | Magazine case 45 pcs | Standard products | PS7241-2A |
| PS7241-2A-F3 | PS7241-2A-F3-A | | Embossed Tape 1 500 pcs/reel | (UL, BSI, CSA | |
| PS7241-2A-F4 | PS7241-2A-F4-A | | | approved) | |

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

| Parameter | | Symbol | Ratings | Unit |
|-------------------------------|--|--------|-------------|---------|
| Diode | Forward Current (DC) | lf | 50 | mA/ch |
| | Reverse Voltage | VR | 5 | V |
| | Power Dissipation | P⊳ | 50 | mW/ch |
| | Peak Forward Current *1 | IFP | 1 | A/ch |
| MOS FET | Break Down Voltage | VL | 400 | V |
| | Continuous Load Current | ١L | 120 | mA/ch |
| | Pulse Load Current ^{*2} (AC/DC Connection) | Ilp | 200 | mA/ch |
| | Power Dissipation | PD | 180 | mW/ch |
| Isolation Voltage *3 | | BV | 1 500 | Vr.m.s. |
| Total Power Dissipation | | Ρτ | 460 | mW |
| Operating Ambient Temperature | | TA | -40 to +85 | °C |
| Storage Temperature | | Tstg | -40 to +100 | °C |

*1 PW = 100 *µ*s, Duty Cycle = 1%

*2 PW = 100 ms, 1 shot

*3 AC voltage for 1 minute at $T_A = 25^{\circ}$ C, RH = 60% between input and output Pins 1-4 shorted together, 5-8 shorted together.

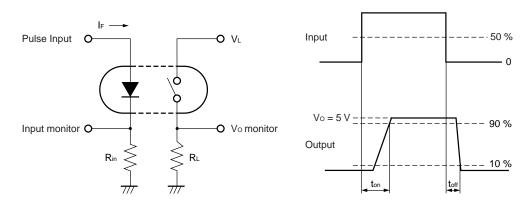
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

| Parameter | Symbol | MIN. | TYP. | MAX. | Unit |
|-----------------------|--------|------|------|------|-------|
| LED Operating Current | lf | 2 | 10 | 20 | mA/ch |
| LED Off Voltage | VF | 0 | | 0.5 | V |

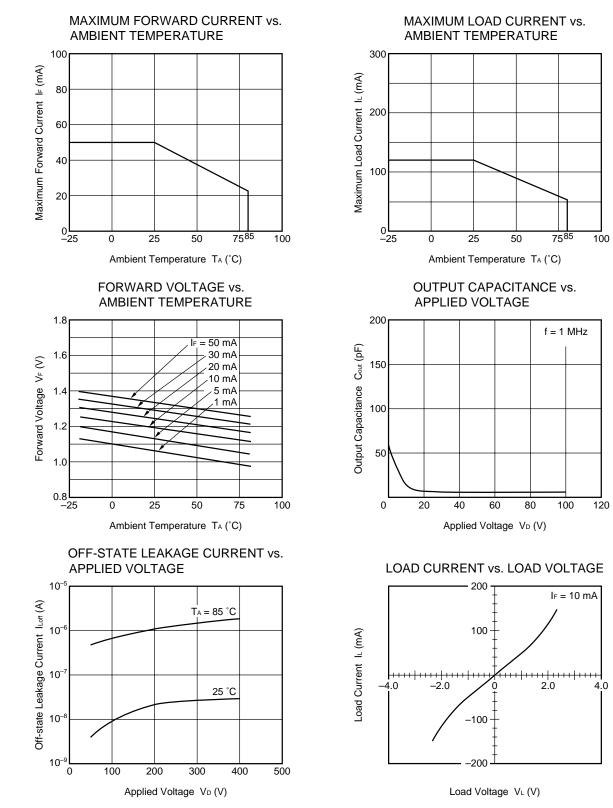
ELECTRICAL CHARACTERISTICS (TA = 25°C)

| | Parameter | Symbol | Conditions | MIN. | TYP. | MAX. | Unit |
|---------|--------------------------------|--------|---|-----------------|------|------|-------|
| Diode | Forward Voltage | VF | IF = 10 mA | | 1.2 | 1.4 | V |
| | Reverse Current | IR | V _R = 5 V | | | 5 | μA |
| MOS FET | Off-state Leakage Current | Loff | V _D = 400 V | | 0.03 | 1.0 | μA |
| | Output Capacitance | Cout | V _D = 0 V, f = 1.0 MHz | | 65 | | pF/ch |
| Coupled | LED On-state Current | IFon | l∟ = 120 mA | | | 2.0 | mA |
| | On-state Resistance | Ron1 | IF = 10 mA, IL = 10 mA | | 21 | 30 | Ω |
| | | Ron2 | I_{F} = 10 mA, I_{L} = 120 mA, $t \leq$ 10 ms | | 16 | 25 | |
| | Turn-on Time ^{*1, 2} | ton | I_{F} = 10 mA, Vo = 5 V, R _L = 500 Ω , | | 0.2 | 1.0 | ms |
| | Turn-off Time ^{*1, 2} | toff | $PW \ge 10 ms$ | | 0.02 | 0.2 | |
| | Isolation Resistance | Rŀo | VI-0 = 1.0 kVDC | 10 ⁹ | | | Ω |
| | Isolation Capacitance | CI-O | V = 0 V, f = 1.0 MHz | | 0.4 | | pF/ch |

*1 Test Circuit for Switching Time



<R> *2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms. Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.



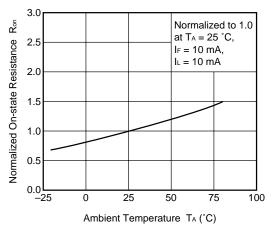
TYPICAL CHARACTERISTICS (TA = 25°C, unless otherwise specified)

Remark The graphs indicate nominal characteristics.

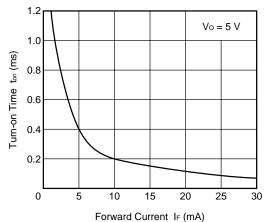
Data Sheet PN10304EJ02V0DS

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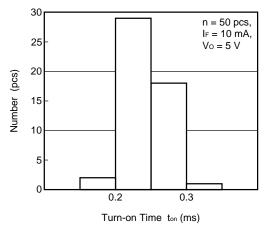
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



TURN-ON TIME vs. FORWARD CURRENT

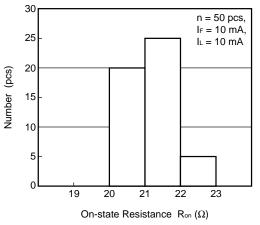


TURN-ON TIME DISTRIBUTION

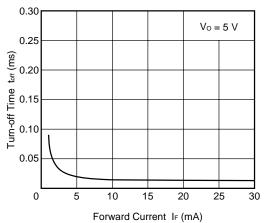


Remark The graphs indicate nominal characteristics.

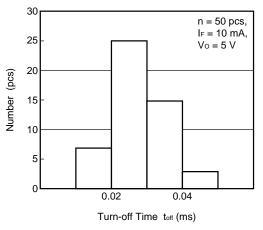
ON-STATE RESISTANCE DISTRIBUTION

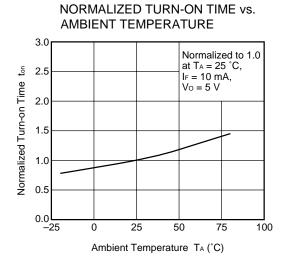


TURN-OFF TIME vs. FORWARD CURRENT



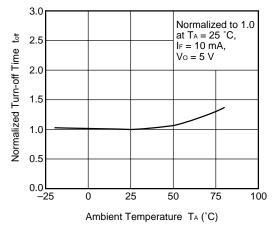
TURN-OFF TIME DISTRIBUTION



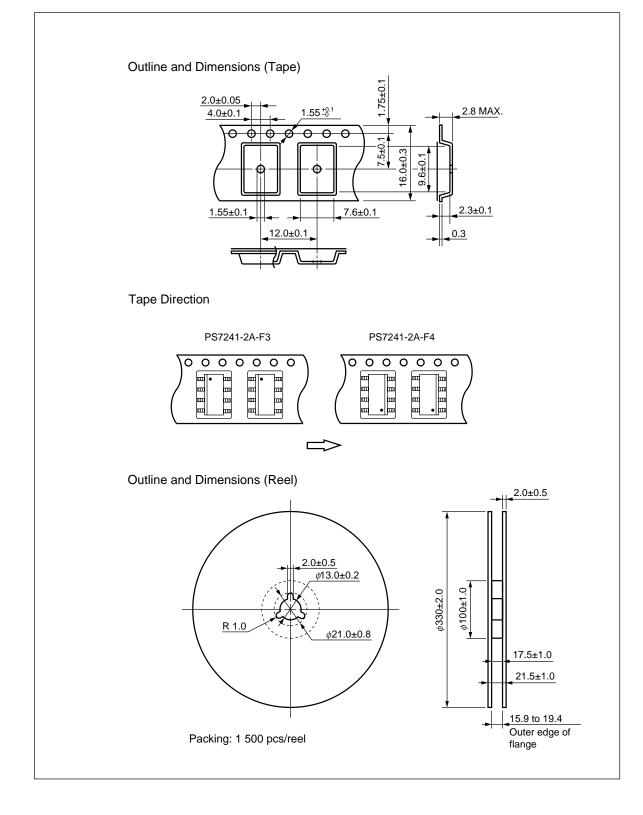


Remark The graphs indicate nominal characteristics.





TAPING SPECIFICATIONS (in millimeters)



RECOMMENDED SOLDERING CONDITIONS

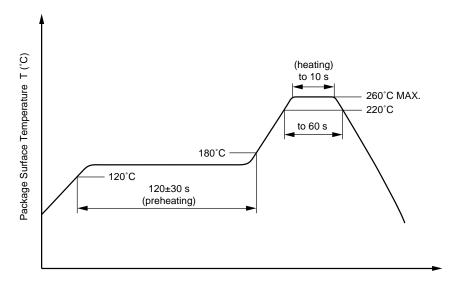
(1) Infrared reflow soldering

- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

| Temperature | 260°C or below (molten solder temperature) |
|---|--|
| • Time | 10 seconds or less |
| Preheating conditions | 120°C or below (package surface temperature) |
| Number of times | One |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a maximum chlorine |

<R> (3) Soldering by soldering iron

| Peak temperature (lead part temperature) | 350°C or below |
|--|---|
| Time (each pins) | 3 seconds or less |
| • Flux | Rosin flux containing small amount of chlorine (The flux with a |
| | maximum chlorine content of 0.2 Wt% is recommended.) |

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

content of 0.2 Wt% is recommended.)

(b) Please be sure that the temperature of the package would not be heated over 100° C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- **1.** Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

| Caution GaAs Products | This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. |
|-----------------------|--|
| | • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. |
| | Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. |
| | Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. |
| | • Do not burn, destroy, cut, crush, or chemically dissolve the product. |
| | • Do not lick the product or in any way allow it to enter the mouth. |

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